

*51.1  
cont'd*

sink. High conductivity gases are admitted into the chamber to accomplish cooling of the article. *EA*

In the claims:

Claim 9, line 11, change "in position" to -- which distance is --

Claim 12, line 15, following "predetermined" insert -- cold --.

Claim 12, line 15 following "level" insert -- compared to the wafer --.

REMARKS

In the action of February 22, 1993, the Examiner noted the omission of an Abstract. An abstract has been added with this amendment. The abstract is word for word the abstract in the parent patent (5,181,556).

*Reptk*

Applicant has amended claim 9 with this amendment to clarify wording which previously was confusing. The intent is to describe equipment in which the article is spaced apart from the heat sink a predetermined distance during movement into position and while in position during treatment or processing. An amendment has also been made to the independent method claim to cause the claim to describe a cooling process.

A rejection has been stated on grounds of double patenting. As had been indicated at the time of filing this continuation application it is intended to file a terminal disclaimer in this application to disclaim that